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Semester Project – Bandgap Reference Voltage

ESPLAB - Electronic and Signal Processing Laboratory

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Abstract

In analog IC design, the design of each block start by choosing a voltage reference that is generally used as power supply voltage or a different important reference. The effect of temperature on this voltage is very important as it can totaly change the way of operating of the circuit. A voltage reference insensitive to tempperature is then a very used design in various application.

Almost all the reference voltage use the bandgap principle, however this bandgap reference can be designed in various ways. One of the main goals of this project is to study the bandgap principle but also to find which structure is the most adapted to a special requirement which is the current consumption. In fact, the final idea is to use a voltage reference for low-power application, and therefore use a structure that will limit the current consumption.

During this report we are going to see the different principle that drive the bandgap reference voltage and then study two different structure choosen for their low current consumption. The report will present the various advantages of each structure and also the many tradeoffs that they reveal.

1 Principle & Specifications

Voltage references have always been an essential component of any system and consequently an important topic to explore. The last decades even total system integration has required all designers to be knowledgeable of this particular topic due to its mixed-signal implications (output impedance, temperature coefficient, etc...)

A general-use (ideal) voltage reference is a circuit used to generate a fixed voltage, V_{ref} , that is independent of the power supply voltage VDD (where $V_{ref} < VDD$), temperature, and process variations. In other words, the ideal reference voltage is independent of PVT. In some cases, we want to design a reference that varies with temperature. For example, if V_{ref} increases with temperature, Fig. 1.2, we say that the reference voltage is proportional to absolute temperature or **PTAT**. If the reference voltage decreases with increasing temperature, Fig. 1.1, the reference is said to be complementary to absolute temperature or **CTAT**.

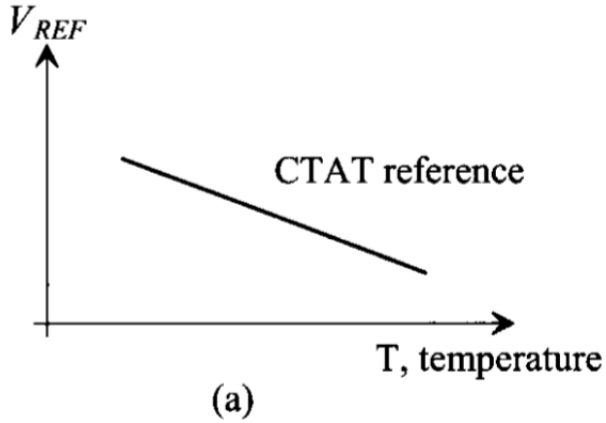


FIGURE 1.1 – CTAT Voltage Evolution

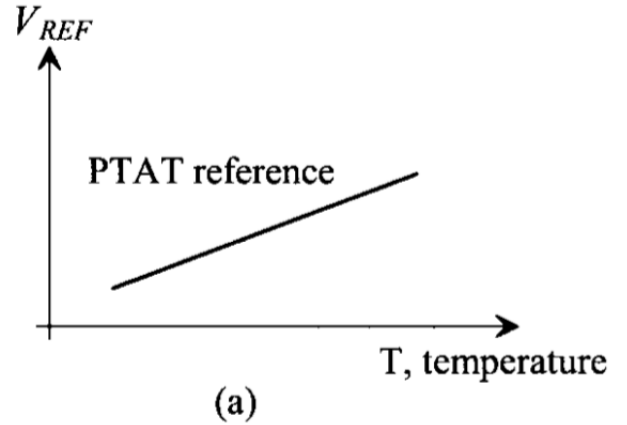


FIGURE 1.2 – PTAT Voltage Evolution

The **PTAT** and **CTAT** references can be used to design a voltage reference that changes very little with temperature called a bandgap reference. We only need to sum the two voltages with the correct coefficient K (Fig. 1.3).

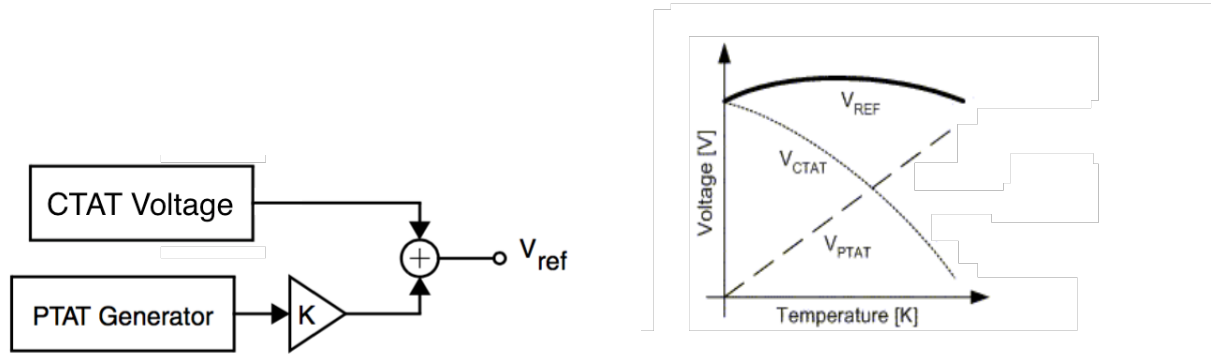


FIGURE 1.3 – General Bandgap Voltage Principle

In a limited library of electronic component, we need to find a characteristic or a mechanism to build a PTAT or CTAT behaviour. The most usual component used in Analog IC design, Bipolar and MOS transistor, will be the key of these construction. In one hand, we can notice that the temperature coefficient of the base-emitter voltage (V_{BE}) is negative, as well as the V_{GS} of a MOS transistor. In the other hand, we can observe that two bipolar or MOS transistor working at a unequal current densities create a voltage that is proportionnal to $U_T = \frac{kT}{q}$ therefore PTAT voltage (Positive Temperature Coefficient - TC).

The bandgap voltage reference will be used in different block, and specially for applications with low power consumption. The design will then take into account some specifications related to these applications. We can resume these main specifications in the next table :

| | Typ | Maximum | Minimum |
|-----------------------------|------------------|-----------------|---------|
| Current Consumption | 1 μA | 3 μA | — |
| Power Supply Voltage | 1.8 V | 2 V | 1.5 V |
| Technology | UMC L180UMC L180 | | |

TABLE 1.1 – Voltage Reference Specifications

2 Generate a CTAT Voltage

2.1 Evolution of V_{BE} with respect to temperature

The base-emitter voltage of a bipolar transistors or, more generally, the forward voltage of a pn-junction diode show a negative TC. For a bipolar device such as represented in the Fig. 2.1

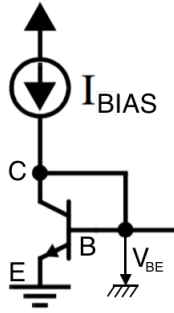


FIGURE 2.1 – Base-emitter Voltage Context

$$V_{BE} = \frac{k_B T}{q} \cdot \ln \left(\frac{I_C}{I_S} \right) \quad (2.1)$$

With I_S , the saturation current of a bipolar transistor. In fact, I_S depend on the temperature through different characteristic n_i and μ_0 for instance. In a first calculation, we suppose that the collector current I_C is independent of the temperature. After calculation (details on Appendix A) we obtain :

$$\frac{\partial V_{BE}}{\partial T} = \frac{V_{BE} - (4 + m)U_T - E_g/q}{T} \quad (2.2)$$

Where $m \approx -3/2$ a process parameter, $E_g \approx 1.12eV$ the bandgap energy of silicon, $U_T = \frac{kT}{q}$ the thermal voltage.

The equation 2.2, reveal the dependence of $\frac{\partial V_{BE}}{\partial T}$ to the magnitude of V_{BE} , the bandgap energy of silicon (thus the name of the voltage reference) and to the temperature itself. In fact, we can do a Taylor serie development of V_{BE} with respect to temperature and we will find that the first order of the development is the dominant term, and it's that term that we are going to focus on. Therefore, we can fix $V_{BE} \approx 700mV$, $T \approx 300K$ and we obtain $\frac{\partial V_{BE}}{\partial T} \approx -1.2mV/K$.

2.2 Bipolar Implementation in CMOS process

The implementation of a bipolar transistor in a CMOS process use a lateral architecture of a bipolar transistor which can be better controled and processed with a much better accuracy than the vertical architecture. In fact, during the process, the depth of oxydation in the silicon is controlled with a very low accuracy whereas the oxydation of a specific area is much more controled and better processed. We then use a lateral transistor, processed and layouted as in the Fig 2.2 :

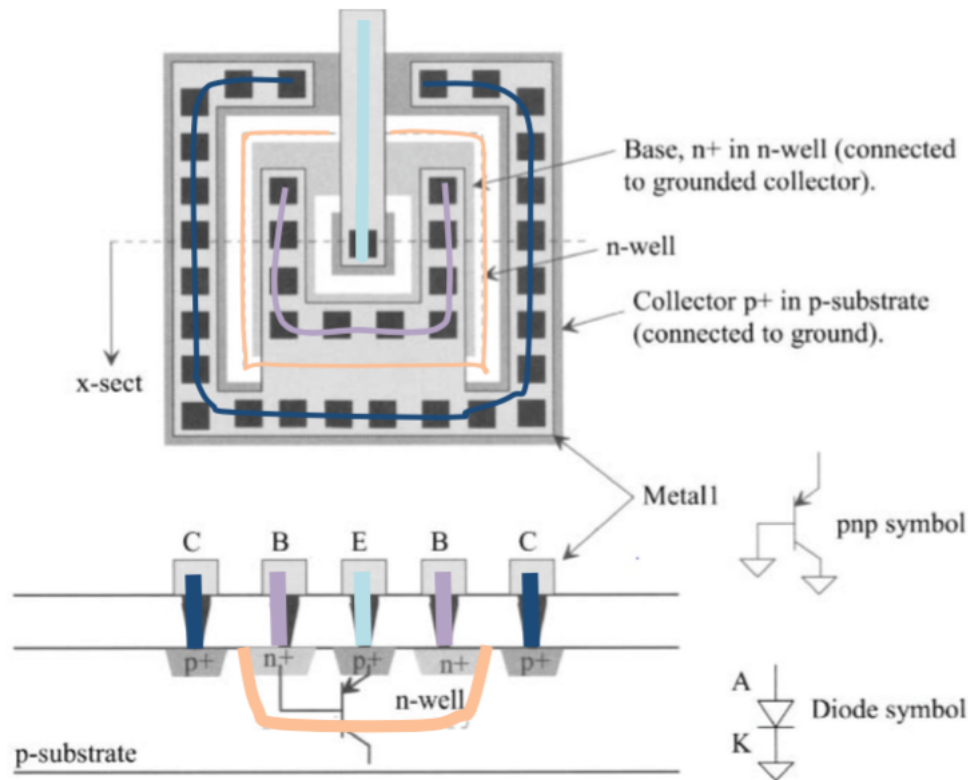


FIGURE 2.2 – Layout of PNP Bipolar Transistor

3 Generate a PTAT Voltage

3.1 Using Base-emitter Voltage

As said in the first chapter, we are going to use two bipolar transistor working in two different current densities, and then measure the difference between their base-emitter voltage. This differential voltage is proportionnal to the thermal voltage, and give us then PTAT behaviour.

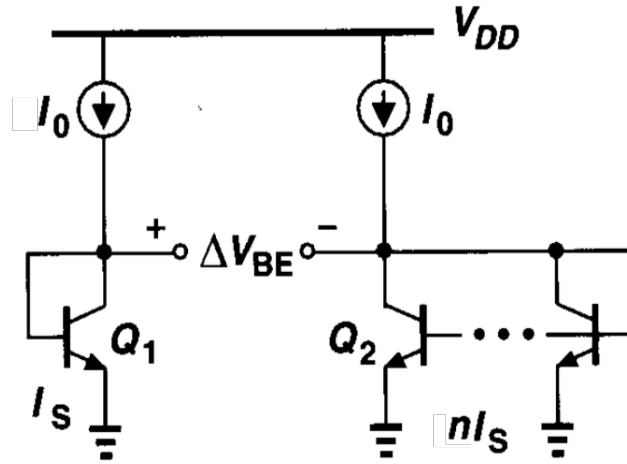


FIGURE 3.1 – Generate a PTAT Voltage

To generate two different current densities we first take two branches, with bipolar transistor perfectly matched. In these two branches will flow the same current I , and in one branch we are going to put in parallel n identical bipolar transistors and one bipolar transistor in the other branch ($I_{S2} = nI_S$ and $I_{S1} = I_S$). Therefore we have :

$$\Delta V_{BE} = V_{BE1} - V_{BE2} \quad (3.1)$$

$$= U_T \ln \left(\frac{I_0}{I_{S1}} \right) - U_T \ln \left(\frac{I_0}{I_{S2}} \right) \quad (3.2)$$

$$= \frac{kT}{q} \cdot \ln(n) \quad (3.3)$$

The final idea is to add this differential-voltage to a CTAT voltage which is not possible in a complete structure, so instead of generating a PTAT differential voltage, we generate a PTAT current which we can be easily copied in another branch.

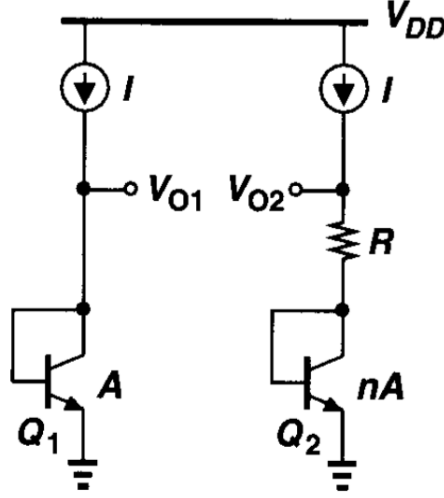


FIGURE 3.2 – Generate a PTAT Current

In this new structure, we need to add a mechanism that will force $V_{O1} = V_{O2}$, concretely we will use a operational amplifier with a high gain to force the two voltages to be equal.

$$V_{O1} = V_{O2} \quad (3.4)$$

$$V_{BE1} = RI + V_{BE2} \quad (3.5)$$

$$I = \frac{\Delta V_{BE}}{R} \quad (3.6)$$

$$= \frac{\frac{kT}{q} \cdot \ln(n)}{R} \quad (3.7)$$

We obtain finally a PTAT current proportional to the thermal voltage that is easier to sum with a CTAT voltage. Moreover we have two parameter n and R , that we can fix to change the temperature coefficient and then cancel the TC of the CTAT branch.

3.2 Using Gate-source Voltage

The same PTAT behaviour can be observed with MOS transistor, in concrete terms we use two transistor M1 and M2, which will operate in weak inversion with two different current densities. This region of operation has quasi the same variations than the bipolar transistor : an exponential dependence of the drain current with respect to the gate-source voltage.

$$I_{DS} = I_{SPECs} \cdot \frac{W}{L} \cdot \exp\left(q \frac{V_{gs} - V_t}{nkT}\right) \quad (3.8)$$

$$I_{SPECs} = 2n\mu_n C_{ox} U_t^2 \quad (3.9)$$

In the same way, we use an Opamp to ensure that the two voltages V_A V_B are equal. We use the same current in the two branches using a current mirror (M_{10} and M_{11}), and we size the transistor M_2 m times larger than M_1 , we then have :

$$V_{GS1} = nU_T \cdot \ln \left(\frac{I_{DS1} \cdot L_1}{I_{SPECs} \cdot W_1} + V_{T0} \right) \quad (3.10)$$

$$V_{GS2} = nU_T \cdot \ln \left(\frac{I_{DS2} \cdot L_2}{I_{SPECs} \cdot W_2} + V_{T0} \right) \quad (3.11)$$

$$\frac{W_2}{L_2} = m \cdot \frac{W_1}{L_1} \quad (3.12)$$

In the same logic we obtain a current I_{R1} which is proportional to ΔV_{GS} , in fact the final theoretical expression of $I_{R1} = \frac{\Delta V_{GS}}{R_1}$ with :

$$\Delta V_{GS} = n \frac{kT}{q} \ln(m) \quad (3.13)$$

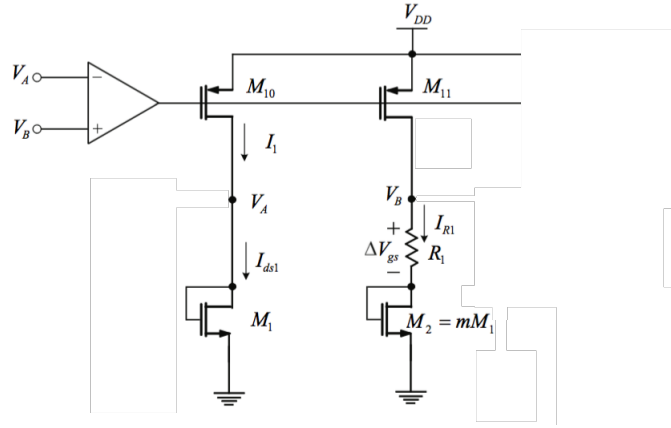


FIGURE 3.3 – Generate a PTAT Current with MOS transistor

The final result is very similar to the bipolar "version", except that for the MOS version, ΔV_{GS} is proportionnal to the slope factor, which add another dependence in temperature. For our use, the variation can be neglected for the dependence of the first order of temperature.

4 Bandgap Voltage

4.1 Current Source - Beta-Multiplier

As we are limited to $3 \mu A$ in current consumption, we are going to limit the current consumption in the current source to the minimum. We decide then to produce a current of 100 nA that we are going to mirror in the different branches to generate a PTAT and a CTAT voltage. To generate this current, we use the structure in the Fig 4.1 :

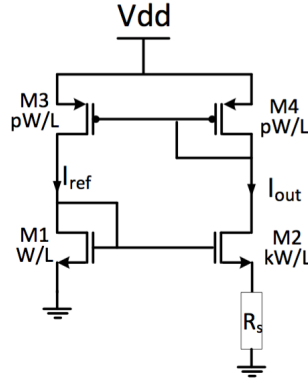


FIGURE 4.1 – Beta-Multiplier Current Source with Cascode

For such low current, the two transistor M1 and M2 operate in weak inversion, and to obtain a good current mirror with respect to mismatch and have then I_{ref} quasi equal to I_{out} we put the transistor M3 and M4 in strong inversion. To determine the variation of the current I_{out} with respect to R_S we use the simplified equation of the drain current in weak inversion, given by the EKV model :

$$I_{out} = I_{spec} \cdot \exp\left(\frac{V_G - nV_S - V_{T0}}{nU_T}\right) \quad (4.1)$$

If we apply this equation to the transistor M1 and M2, with M2 k times larger than M1, we have the final expression of I_{out} :

$$I_{out} = I_{ref} = \frac{U_T \cdot \ln(k)}{R_S} \quad (4.2)$$

The main problem of this structure is the dependence of the current I_{out} to the absolute value of R_S , which make the current depend on process variation. In fact, the absolute value of R_S have a global precision of $\pm 20 \%$.

The other important dependence of I_{out} is to the variation of V_{DD} by ΔV_{DD} . Therefore, we have to do a small signal analysis of the variation ΔI_{out} of I_{out} with a variation of V_{DD} by ΔV_{DD} . The details of the calculation are shown in the Appendix B.1, we have finally :

$$\frac{\Delta I_{out}}{\Delta V_{DD}} \approx \frac{1}{r_{on}} + \frac{2}{r_{op}} \quad (4.3)$$

With r_{on} and r_{op} respectively the output resistance of the NMOS and PMOS transistor, as shown in the Appendix B.1 . Therefore, to decrease the dependence of I_{out} to V_{DD} , we have to increase r_{on} and r_{op} , to do that we are going to use a cascode structure for the NMOS transistor and increase the length of the PMOS transistor to increase r_{op} . The final structure is shown on Fig 4.2 :

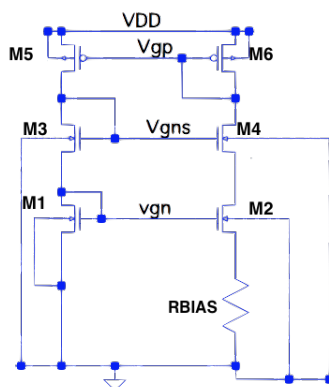


FIGURE 4.2 – Beta-Multiplier Current Source with Cascode

As the transistor M1 and M2 should work on weak inversion we choose an inversion coefficient $IC(M1) = 0.1$ and we choose $k = 4$, so $\frac{W_2}{L_2} = 4 \cdot \frac{W_1}{L_1}$. And finally, the transistor M5 and M6, should work on strong inversion, so we choose an inversion coefficient $IC = 30$ so we can have a very large value of L_5 and L_6 . Finally :

| | |
|-------------------------------|---------------------------------|
| $W_1 = 4 \text{ }\mu m$ | $L_1 = 180 \text{ nm}$ |
| $W_2 = 16 \text{ }\mu m$ | $L_2 = 180 \text{ nm}$ |
| $W_3 = W_4 = 5 \text{ }\mu m$ | $L_3 = L_4 = 250 \text{ nm}$ |
| $W_5 = W_6 = 250 \text{ nm}$ | $L_5 = L_6 = 3.2 \text{ }\mu m$ |

TABLE 4.1 – Beta-Multiplier transistor dimension

4.2 Single Stage OTA

The specifications impose us a very low current consumption (max $3 \mu A$), though the amplifier need to have a very high gain so we can have $V_{O1} = V_{O2}$, Fig. 3.2, and to achieve that we need enough current to have enough gain, so we need to find the good compromise between the High gain and current consumption specifications, we decide to fix a gain $A_0 = 500 \approx 50 \text{ dB}$ with a current of 500 nA .

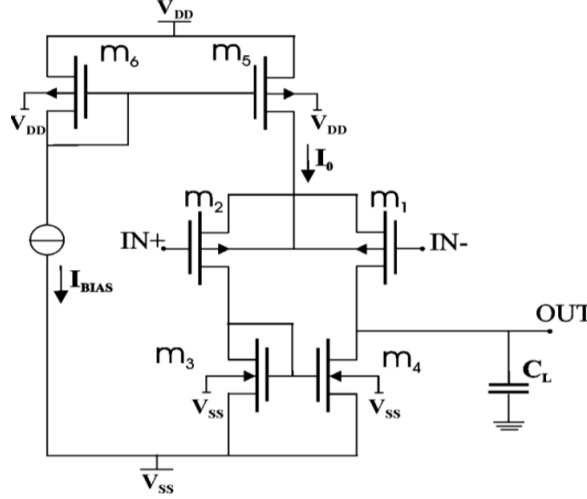


FIGURE 4.3 – OTA with PMOS differential pair

The transistor $m1$ and $m2$ have the same size and the transistor $m3$ and $m4$ too. We choose a current $I_D(m5) = I_0 = 500 \text{ nA}$, we have then $I_D(m1, m2, m3, m4) = I_0/2 = 250 \text{ nA}$. We fix also the gain band width (GBW) to 10 kHz and a load capacitance $C_L = 1 \text{ pF}$. We can use the expression of the unity gain frequency to express $g_m(m1, m2)$:

$$g_m(m1, m2) = GBW \cdot C_L = 10 \cdot 10^{-9} \cdot \Omega^{-1} \quad (4.4)$$

We have the value of g_m and the current flowing on the transistors $m1$ and $m2$ we can now determine their inversion coefficient and then deduce the $\frac{W}{L}$ of the differential pair :

$$\frac{g_m}{I} = \frac{1}{nU_T} \cdot \frac{2}{\sqrt{1 + 4IC} + 1} \quad (4.5)$$

$$\frac{W}{L}(m1, m2) = \frac{I_0/2}{I_{spec\Box} \cdot IC} \quad (4.6)$$

We know that the output resistance is related to the length of the transistor $m1$ and $m4$ due to the channel length modulation, eq. 4.7, moreover if we do the small signal analysis we can also link the gain A_0 to R_{out} , eq 4.8. Finally, to size the NMOS current mirror we fix the overdrive voltage $V_{ov} = 200 \text{ mV}$ and deduce the W/L thanks to Eq 4.9.

$$L(m1, m4) = I_0/2 \cdot R_{out} \left(\frac{1}{U_{aN}} + \frac{1}{U_{aP}} \right) \quad (4.7)$$

$$A_0 = R_{out} \cdot g_m(m1, m2) \quad (4.8)$$

$$\frac{W}{L}(m3, m4) = \frac{2n \cdot I_0/2}{\mu_n C_{ox} V_{ov}^2} \quad (4.9)$$

The final dimension of the transistors are resumed in the next table :

| | |
|---------------------------|--------------------------|
| $W_1 = W_2 = 1.47 \mu m$ | $L_1 = L_2 = 5.31 \mu m$ |
| $W_3 = W_4 = 12.05 \mu m$ | $L_3 = L_4 = 5.31 \mu m$ |
| $W_5 = 1.25 \mu m$ | $L_5 = 3.2 \mu m$ |

TABLE 4.2 – OTA transistor dimension

4.3 Overall circuits

4.3.1 Bandgap Voltage Reference

The final circuits is composed of the PTAT branches using a current mirror to copy the current in the two branches, these two transistor (M_3, M_4) are biased thanks to the beta-multiplier current source, in fact in each branch we use a current of 250 nA. The PTAT current is copied in the third branch (right one) and converted to a PTAT voltage thanks to the resistance R_2 and then added to the base-emitter voltage of the PNP bipolar transistor (CTAT).

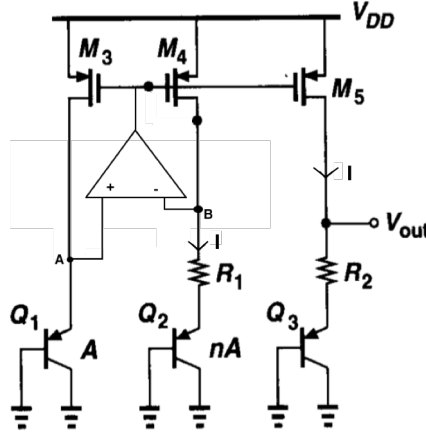


FIGURE 4.4 – Bandgap Voltage Reference

$$V_{ref} = V_{BE3} + \frac{R_2}{R_1} \Delta V_{BE} = V_{BE3} + \frac{R_2}{R_1} \cdot \frac{kT}{q} \ln(n) \quad (4.10)$$

The final equation to cancel the temperature

$$\frac{\partial V_{ref}}{\partial T} = \frac{\partial V_{BE3}}{\partial T} + \frac{R_2}{R_1} \cdot \frac{k}{q} \ln(n) \quad (4.11)$$

$$\frac{R_2}{R_1} = - \frac{\frac{\partial V_{BE3}}{\partial T}}{\frac{k}{q} \ln(n)} \quad (4.12)$$

| | |
|------------------------------------|-------------------------------|
| $W_3 = W_4 = W_5 = 625 \text{ nm}$ | $L_3 = L_4 = L_5 = 3.2 \mu m$ |
| $R_1 = \Omega$ | $R_2 = \Omega$ |
| $n = 4n = 4$ | |

TABLE 4.3 – Bandgap Voltage Reference Dimensions

The final current consumption is $200 \text{ nA} + 3 \cdot 250 \text{ nA} + 500 \text{ nA} = 1.450 \mu\text{A}$, the final voltage is quasi-independent of the temperature but the current generated on the third branch is PTAT, we have only a bandgap voltage. Moreover for low power applications it's very interesting to have a voltage inferior to 1V, as it's usually used in low power device. The cancelation of the two temperature coefficient is done thanks to the quotient of the two resistance, so the cancelation doesn't depend on process variation, in fact if the process create an imprecision of +20 % on R_1 , for instance, the resistance R_2 is also 20 % higher than the nominal value.

We obtain then a theoretical Bandgap voltage reference independent of temperature, process variation and power supply voltage.

4.3.2 Sub-1V Bandgap Current and Voltage Reference

A problem with the bandgap circuits described so far is that they are not compatible with low power applications, that usually need a reference voltage sub 1V. The fundamental problem is that the previous circuits produce the CTAT voltage across a pn-junction and a PTAT voltage scaled to provide temperature- independence. Together, these voltages exceed 1 V. The solution is to sum currents : one CTAT and one PTAT, passing them through a resistor to form a temperature-insensitive reference voltage below 1 V. A low-voltage bandgap circuit based on this idea is shown in Fig. 4.5. The feedback loop formed by the amplifier and current mirror Q1 /Q2 ensures that the voltages at the drains of Q1 and Q2 are very well matched and equal to the base-emitter voltage drop across diode D , V_{BE1} , which is inversely proportional to absolute temperature.

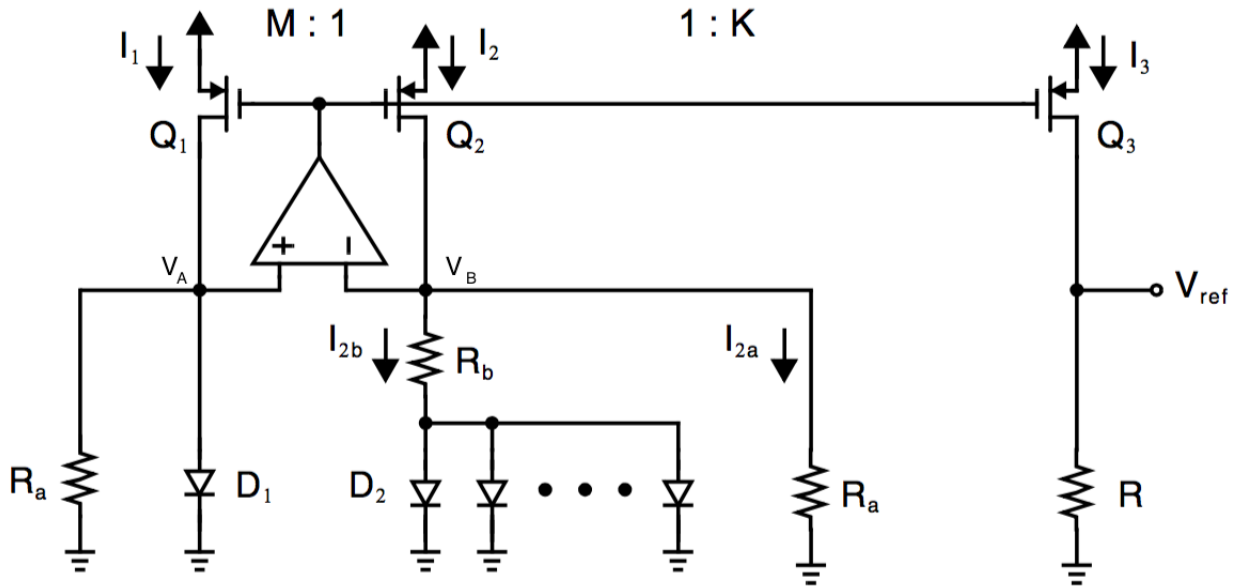


FIGURE 4.5 – Bandgap Voltage and Current Reference

The CTAT voltage V_{BE1} and PTAT ΔV_{BE} are converted into the currents I_{2a} and I_{2b} by the resistors R_a (4.13) and R_b , (4.13) respectively. These two currents are summed at the drain of Q2 and mirrored to device Q3 . The resulting current then passes back through resistor R to yield the reference output.

$$I_{2a} = \frac{V_{BE1}}{R_a} \quad (4.13)$$

$$I_{2a} = \frac{\Delta V_{BE}}{R_b} \quad (4.14)$$

The values M , N , R_a , and R_b are chosen to ensure that the inverse temperature coefficient of the

first term is precisely cancelled by the positive temperature coefficient of the second term. Notice that nowhere are there DC voltages exceeding V_{BE} , so this circuit has been used with supply voltages as low as 0.8 V. The values of K and R can be chosen to scale the actual value of the reference potential at V_{ref} , while the values of N , R_a and R_b are chosen to cancel the negative and positive temperature coefficients of the first and second terms in (4.15).

$$V_{ref} = V_{BE1} \frac{KR}{R_a} + \frac{kT}{q} \ln(N) \frac{KR}{R_b} \quad (4.15)$$

This structure presents a first problem which is the size of the resistance. The voltage V_A should be fixed at at least 0.7 V, as we already impose the current on this branch through the beta multiplier (250 nA), we have then a resistance R_a which is around 3 M Ω and R_b is around a 100 k Ω , this is to add to the large area took by the bipolar transistor (5 PNP of 50x50 μm^2). Despite the area issue, we have a very symmetric structure, which generate both a bandgap voltage and current.

5 Results after Simulation

5.1 Dependence to VDD

The current source have been tested in two different ways, first we verified the influence of the cascode structure, initially designed to reduce the effect of the variations of V_{DD} on the absolute value of I_{ref} (4.1), then we will study the variation of the current I_{ref} with respect to the variation of the absolute value of R_{BIAS} , (4.2).

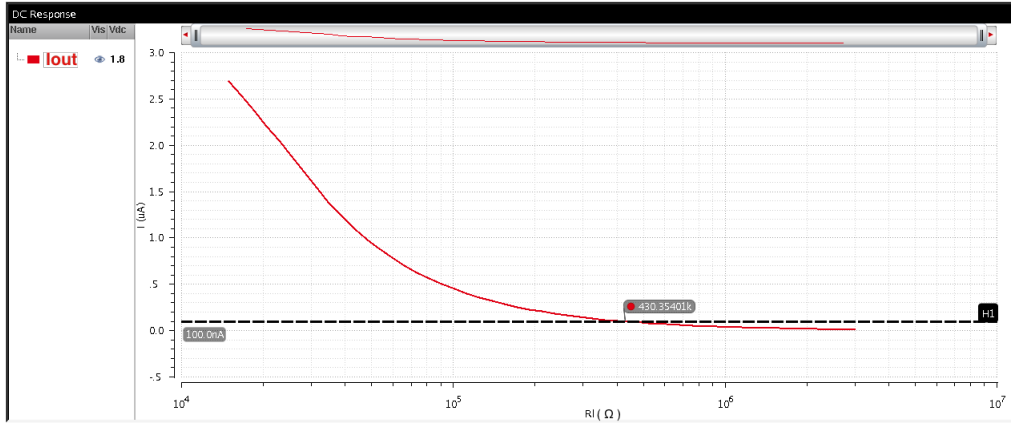
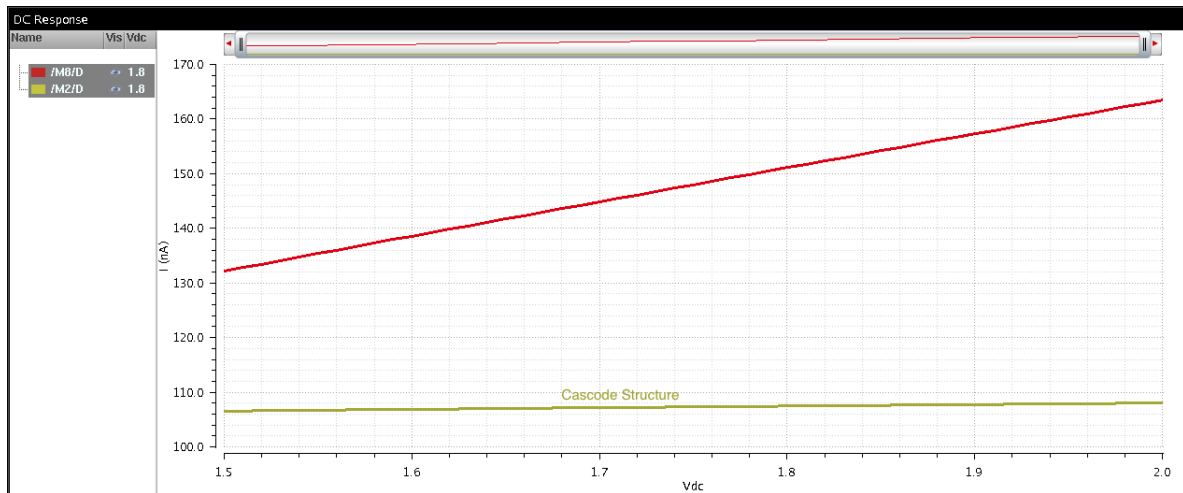


FIGURE 5.1 – Characteristic of the Beta Multiplier Current Source

We clearly see that the output current is inversely proportional to the value of the resistance as predicted in the theoretical part, nevertheless we notice that the absolute value of the current is shifted by an offset compared to the theoretical results. This offset is probably due to the simplification done on the expression of the current with respect to the gate-source voltage of the MOS transistor, in fact the channel modulation length was not considered in the equation 4.1, if we verify by calculation we find almost the same offset. We have also noticed on the previous part, that this structure is process dependent because the absolute value of the output current depend on the value of a resistance, nevertheless for the range of current we try to generate (~ 100 nA), we can notice on the characteristic that the local slope of the curve around 100 nA is very low, so an imprecision on the value of the resistance won't impact that much the absolute value of the current.



To conclude, we can see that the use of a cascode structure is very efficient, such as the variation of I_{out} with respect to V_{DD} has been divided by 5 passing from the non-cascode structure to the cascode structure. Finally we have succeeded to build a current source which is quasi-independent of the power supply and we have reduced the dependency to process variation.

5.2 Single Stage OTA

The only characteristic of the OTA that interest us here is the gain A_0 that we can measure through a frequency analysis :

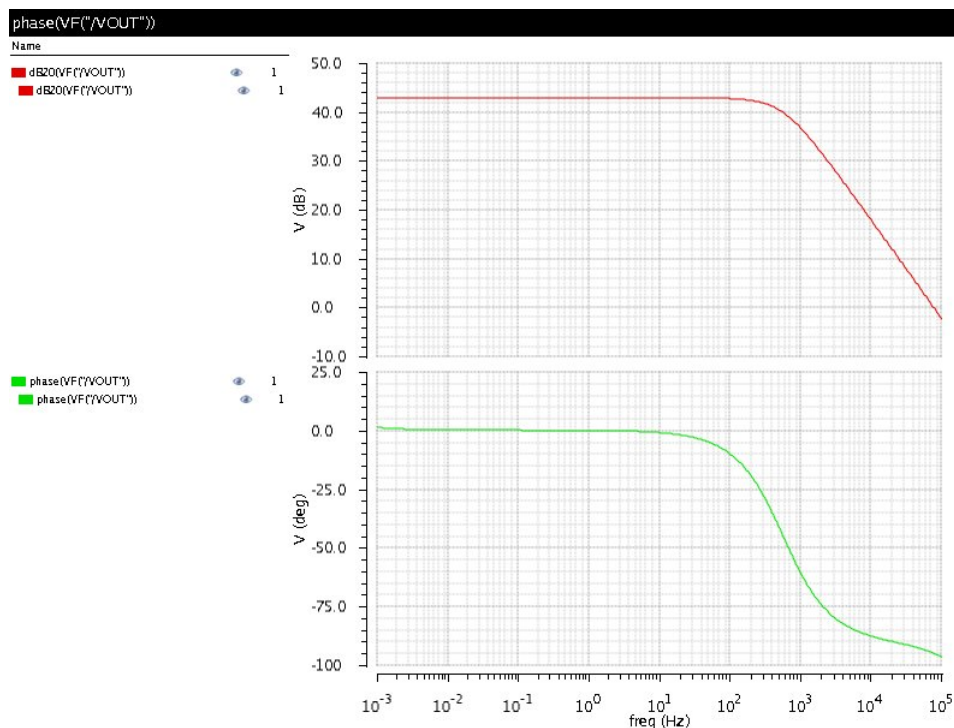


FIGURE 5.2 – OTA single stage frequency analysis

The final result are close to the calculation we have done, we can see that $A_0 \approx 43dB$ which was the specifications of the OTA on the theoretical analysis

5.3 Temperature Dependence

The result that we are going to present here are related to the second structure (sub 1V Bandgap), such as most conclusions are very closed between the two structure. In fact, except the fact that the first structure give us only a Bandgap Voltage higher than one Volt, whereas the second structure provide us a Bandgap Voltage and Current, with a voltage reference inferior to 1V, the main conclusions of the simulations are very close.

First, if we use the first OTA structure, with a single stage amplification we obtain for the second structure the next results :

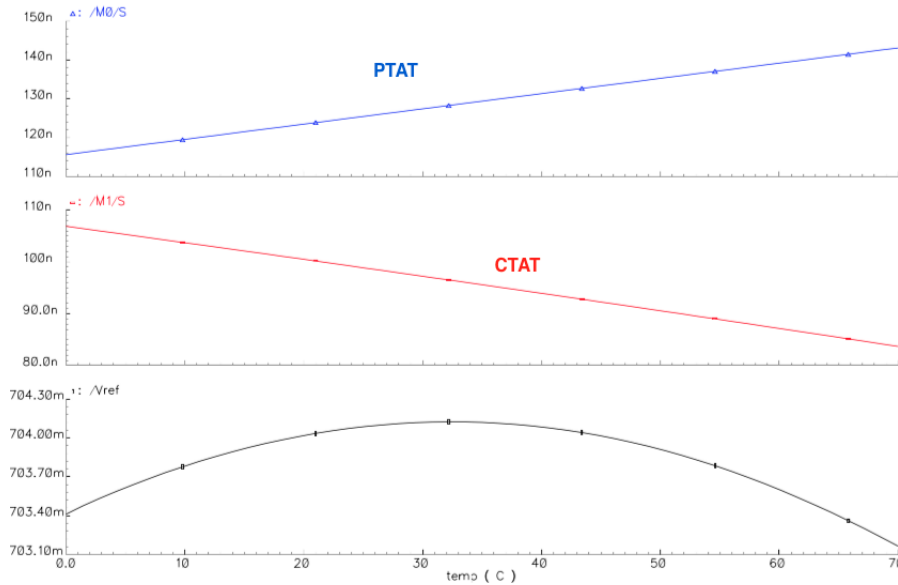


FIGURE 5.3 – Final Bandgap Voltage Reference

If we quantify the final variation of V_{ref} with respect to temperature, we obtain a variation of $200ppm/K$, which is not an acceptable result, in fact with a bandgap structure we can at least have a final variation around the $50 ppm/K$. After more simulation we can observe that the two voltages (Fig. 4.5) V_A and V_B are too different (200 mV difference). The main cause of this difference is the operational amplifier which clearly haven't enough gain to force the two voltages to be at the same level, despite the fact that a previous test with an ideal amplifier with the same gain gave a much better result. In fact, the common mode predicted and used in the frequency analysis is not the one in the real loop of the bandgap structure.

We tried then to cascade the first amplifier with a second one very similar , in fact the second one is a single stage OTA, with a differential pair composed of NMOS transistor and a PMOS mirror current. The frequency analysis showed that the gain of this new cascaded OTA can go to 3000 which is clearly enough for our application.

After testing the bandgap circuits with this OTA, we can observe that the two voltages V_A and V_B can not depass 0.3 V. In fact, the loop generated by the OTA have a point of stability near this voltage, if we don't force some initial condition.

In fact, the same test with initial condition stabilize the two voltages V_A and V_B around the voltage that we want (0.7V), but without these initial condition, in other words when the circuits start from zero, the loop find a local point of stability around 0.2 V which stop our circuit from working. Unlikely, if V_A and V_B are blocked at 0.3 V, the PNP bipolar transistor are not working in saturation and have a total different behaviour with respect to temperature, moreover the resistance have no effect on the variation of the temperature coefficient.

5.4 Layout

Unfortunately, we did not have the time to go very far on the design to have an extracted layout and run simulations to see the effect of the layout and the matching on our circuit. However we have done a layout of the final circuit, first to measure the surface taken by the device and also to have to voltage reference on PTAT and the other CTAT to see if the layout doesn't show any problem on the behaviour of the CTAT or PTAT structure.

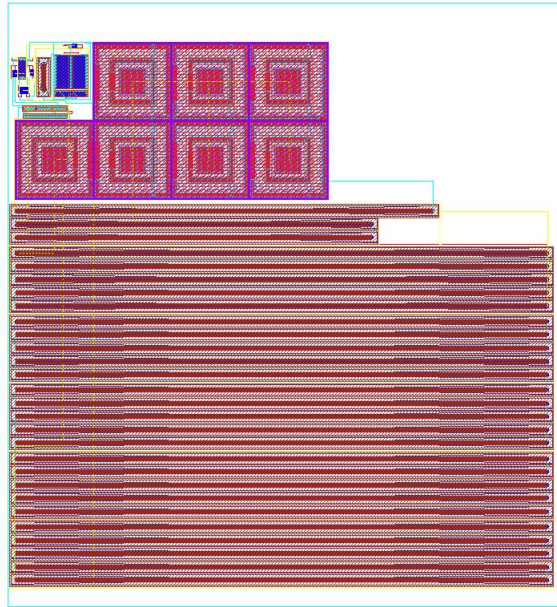


FIGURE 5.4 – Final Bandgap Voltage Reference

The screen-shot of the layout show the problem we have raised on the theoretical part, the resistances and the bipolar transistor take the major silicon surface whereas the OTA, the beta multiplier and the current mirrors take 1/10 of the surface. This may be the principle reason to use MOS transistor to generate the PTAT reference, without forgetting that they are much more difficult to design because we use the MOS in weak inversion.

Conclusion

During this semester project, I had the opportunity to discover another topic related to analog IC design, which is the dependency with respect to temperature. I had the occasion to start my first research on this topic, studying the bandgap principle and choosing, analysing the first structures and schematics.

I had also the chance to experiment the challenge related into building a structure with a very low current consumption and get deeper in my knowledge of the operation of a MOS transistor in such low current. Despite the fact the final result isn't what I expected when I started this project, I have chosen a very interesting structure and raised all the tradeoffs and resolved almost all of them. Part by part, I have divided the various section of the structure and highlighted the key point for designing each part and then point out the problem and the drawbacks of the various choices we have made.

The final result is two possible structure, the first one with a bandgap voltage reference over 1V with a current consumption lower than $3\ \mu A$, insensitive to temperature, process variation and power supply voltage. The second structure give us a bandgap voltage and current reference, with a voltage reference inferior to 1V which is very interesting for low-power application, the problem raised by this structure is the size of the resistance that are very huge and take the major surface on the silicon. The common problem raised of this two structure is the design of the OTA, in fact we need an OTA with enough high gain that won't stop the bipolar transistor of working in saturation because of a local point of stability that put a stop to our circuit.

Annexes

A Evolution of V_{BE} with respect to temperature

The details of the calculation of the dependence of V_{BE} to temperature. We first develop the temperature dependence :

$$V_{BE} = \frac{k_B T}{q} \cdot \ln \left(\frac{I_C}{I_S} \right) \quad (\text{A.1})$$

$$I_S \propto \mu kT n_i^2 \quad (\text{A.2})$$

$$\mu \propto \mu_0 T^m \quad (\text{A.3})$$

$$n_i^2 \propto T^3 \cdot \exp \left(\frac{E_g}{kT} \right) \quad (\text{A.4})$$

With μ the mobility of the carriers, n_i the intrinsic carrier concentration of silicon and $E_g \approx 1.12\text{eV}$ the bandgap energy of silicon.

We introduce a parameter b , which is a proportionality factor :

$$I_S = bT^{4+m} \cdot \exp \left(\frac{E_g}{kT} \right) \quad (\text{A.5})$$

Once we have developed the expression with respect to T , we start to derive the expression :

$$\frac{\partial V_{BE}}{\partial T} = \frac{\partial U_T}{\partial T} \cdot \ln \left(\frac{I_C}{I_S} \right) + \frac{\partial I_S}{\partial T} \cdot \frac{U_T}{I_S} \quad (\text{A.6})$$

$$\frac{\partial I_S}{\partial T} = b(4+m)T^{3+m} \cdot \exp \left(\frac{E_g}{kT} \right) + bT^{4+m} \left(\exp \left(\frac{E_g}{kT} \right) \right) \cdot \frac{E_g}{kT^2} \quad (\text{A.7})$$

$$\frac{U_T}{I_S} \frac{\partial I_S}{\partial T} = (4+m) \frac{U_T}{T} + \frac{E_g}{kT^2} \cdot U_T \quad (\text{A.8})$$

We obtain finally :

$$\frac{\partial V_{BE}}{\partial T} = \frac{U_T}{T} \ln \left(\frac{I_C}{I_S} \right) - (4+m) \frac{U_T}{T} - \frac{E_g}{kT^2} \cdot U_T \quad (\text{A.9})$$

$$\frac{\partial V_{BE}}{\partial T} = \frac{V_{BE} - (4+m)U_T - E_g/q}{T} \quad (\text{A.10})$$

B Output resistance of Beta Multiplier Current Source

We can first draw the small signal schematic :

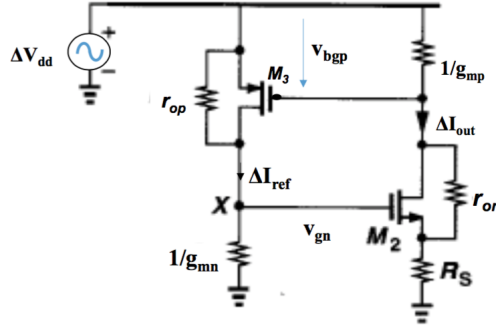


FIGURE B.1 – Small Signal Analysis

We have the in the right branch :

$$\Delta V_{DD} = \frac{\Delta I_{out}}{g_{mp}} + R_s \cdot \Delta I_{out} + r_{on} \cdot (\Delta I_{out} - g_{mn}(M2) \cdot v_{gn} + n \cdot g_{mn}(M2) \cdot R_S \Delta I_{out}) \quad (B.1)$$

$$\Delta V_{DD} \approx 3 \cdot r_{on} \Delta I_{out} - 2 \cdot r_{on} g_m v_{gn} \quad (B.2)$$

We have the in the left branch :

$$\frac{\Delta V_{DD} - v_{gn}}{r_{op}} + g_{mp} \frac{\Delta I_{out}}{g_{mp}} = g_{mn} v_{gn} \quad (B.3)$$

$$g_{mn} v_{gn} \approx \frac{\Delta V_{DD}}{r_{op}} + \Delta I_{out} \quad (B.4)$$

Finally we have :

$$\frac{\Delta I_{out}}{\Delta V_{DD}} \approx \frac{1}{r_{on}} + \frac{2}{r_{op}} \quad (B.5)$$

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